

RESIN COMPOSITION, COPPER FOIL WITH RESIN, DIELECTRIC LAYER,
COPPER-CLAD LAMINATE, CAPACITOR ELEMENT,
AND PRINTED WIRING BOARD WITH BUILT-IN CAPACITOR

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ABSTRACT

A resin composition for use in a dielectric layer of a capacitor is provided that can control a decrease in capacitance or dielectric constant at high temperature and ensure high dielectric characteristics and high adhesion of the composition to a circuit. The resin
10 composition contains a resin component containing an epoxy resin, a diamine compound, and a polyimide resin; and a dielectric filler composed of a metal oxide containing at least two elements selected from the group consisting of Ba, Ti, Sr, Pb, Zr, La, Ta, and Bi. The content of the dielectric filler is 60 to 85 parts by weight on the basis of 100 parts by weight of solid content in the resin composition.

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No suitable figure